Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, LVD, POR, WDT
Number of I/O	11
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f639-e-ss

14-Pin Diagram (PDIP, SOIC, TSSOP)

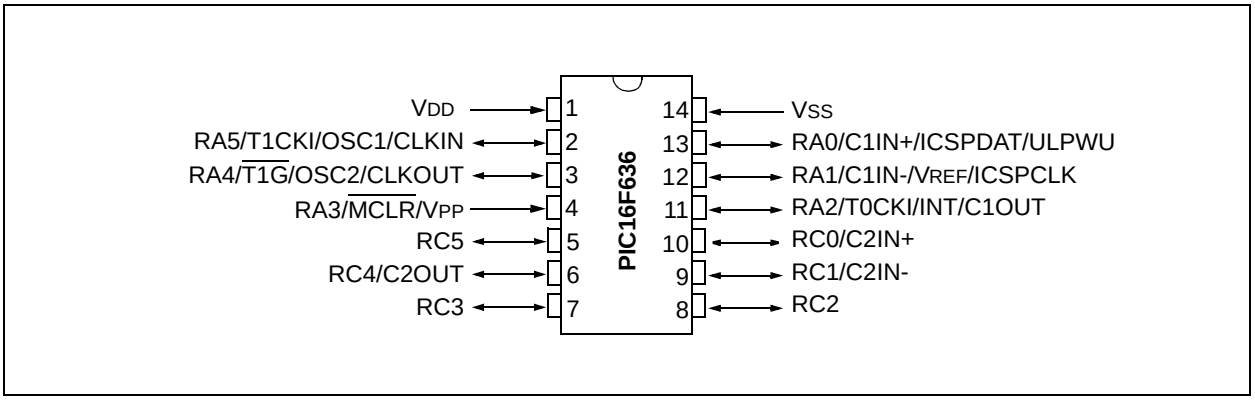


TABLE 2: 14-PIN SUMMARY (PDIP, SOIC, TSSOP)

I/O	Pin	Comparators	Timer	Interrupts	Pull-ups	Basic
RA0	13	C1IN+	—	IOC	Y	ICSPDAT/ULPWU
RA1	12	C1IN-	—	IOC	Y	VREF/ICSPCLK
RA2	11	C1OUT	T0CKI	INT/IOC	Y	—
RA3(1)	4	—	—	IOC	Y(2)	MCLR/VPP
RA4	3	—	T1G	IOC	Y	OSC2/CLKOUT
RA5	2	—	T1CKI	IOC	Y	OSC1/CLKIN
RC0	10	C2IN+	—	—	—	—
RC1	9	C2IN-	—	—	—	—
RC2	8	—	—	—	—	—
RC3	7	—	—	—	—	—
RC4	6	C2OUT	—	—	—	—
RC5	5	—	—	—	—	—
—	1	—	—	—	—	VDD
—	14	—	—	—	—	VSS

Note 1: Input only.

2: Only when pin is configured for external MCLR.

TABLE 2-1: PIC12F635 SPECIAL FUNCTION REGISTERS SUMMARY BANK 0

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR/BOR/ WUR	Page
Bank 0											
00h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	32,137
01h	TMR0	Timer0 Module Register								xxxx xxxx	61,137
02h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	32,137
03h	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	26,137
04h	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	32,137
05h	GPIO	—	—	GP5	GP4	GP3	GP2	GP1	GP0	--xx xx00	47,137
06h	—	Unimplemented								—	—
07h	—	Unimplemented								—	—
08h	—	Unimplemented								—	—
09h	—	Unimplemented								—	—
0Ah	PCLATH	—	—	—	Write Buffer for upper 5 bits of Program Counter					---0 0000	32,137
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RAIE	T0IF	INTF	RAIF(2)	0000 000x	28,137
0Ch	PIR1	EEIF	LVDIF	CRIF	—	C1IF	OSFIF	—	TMR1IF	000- 00-0	30,137
0Dh	—	Unimplemented								—	—
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1								xxxx xxxx	64,137
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1								xxxx xxxx	64,137
10h	T1CON	T1GINV	TMR1GE	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{T1SYNC}$	TMR1CS	TMR1ON	0000 0000	68,137
11h	—	Unimplemented								—	—
12h	—	Unimplemented								—	—
13h	—	Unimplemented								—	—
14h	—	Unimplemented								—	—
15h	—	Unimplemented								—	—
16h	—	Unimplemented								—	—
17h	—	Unimplemented								—	—
18h	WDTCON	—	—	—	WDTPS3	WDTPS2	WDTPS1	WDTPS0	SWDTEN	---0 1000	144,137
19h	CMCON0	—	COUT	—	CINV	CIS	CM2	CM1	CM0	-0-0 0000	79,137
1Ah	CMCON1	—	—	—	—	—	—	T1GSS	CMSYNC	---- --10	82,137
1Bh	—	Unimplemented								—	—
1Ch	—	Unimplemented								—	—
1Dh	—	Unimplemented								—	—
1Eh	—	Unimplemented								—	—
1Fh	—	Unimplemented								—	—

Legend: – = Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented

Note 1: Other (non Power-up) Resets include $\overline{MCLR}$ Reset and Watchdog Timer Reset during normal operation.

2: $\overline{MCLR}$ and WDT Reset do not affect the previous value data latch. The RAIF bit will be cleared upon Reset but will set again if the mismatch exists.

3.5.2.1 OSCTUNE Register

The HFINTOSC is factory calibrated but can be adjusted in software by writing to the OSCTUNE register (Register 3-2).

The default value of the OSCTUNE register is '0'. The value is a 5-bit two's complement number.

When the OSCTUNE register is modified, the HFINTOSC frequency will begin shifting to the new frequency. Code execution continues during this shift. There is no indication that the shift has occurred.

OSCTUNE does not affect the LFINTOSC frequency. Operation of features that depend on the LFINTOSC clock source frequency, such as the Power-up Timer (PWRT), Watchdog Timer (WDT), Fail-Safe Clock Monitor (FSCM) and peripherals, are *not* affected by the change in frequency.

REGISTER 3-2: OSCTUNE: OSCILLATOR TUNING REGISTER

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	TUN4	TUN3	TUN2	TUN1	TUN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **TUN<4:0>:** Frequency Tuning bits

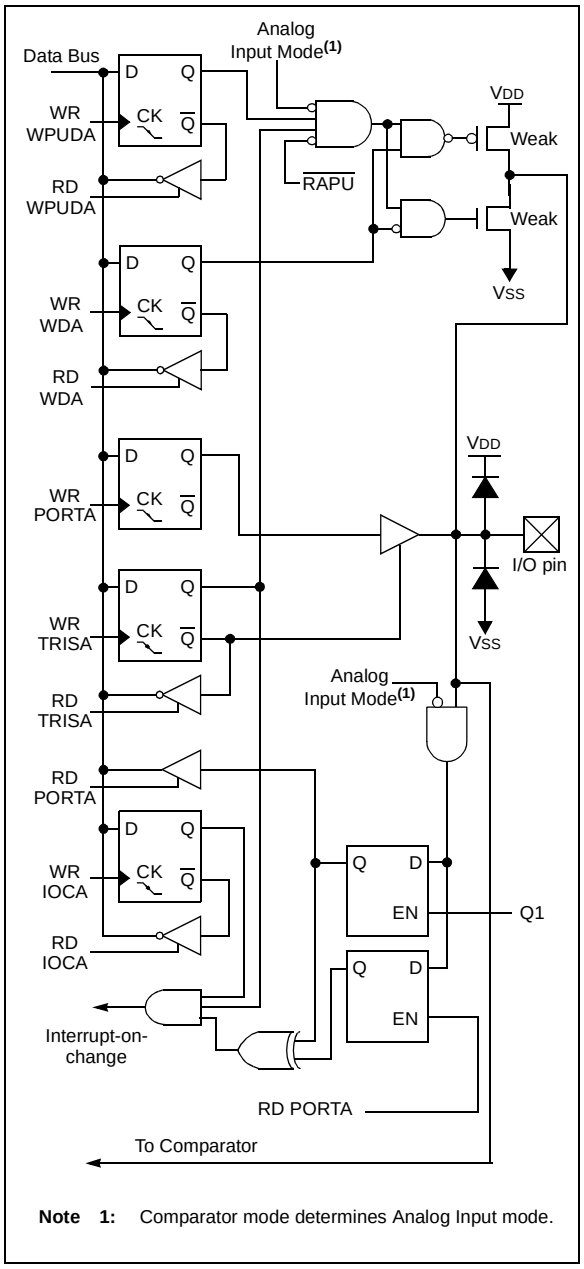
01111 = Maximum frequency
01110 =
•
•
•
00001 =
00000 = Oscillator module is running at the calibrated frequency.
11111 =
•
•
•
10000 = Minimum frequency

4.2.4.2 RA1/C1IN-/VREF/ICSPCLK

Figure 4-2 shows the diagram for this pin. The RA1 pin is configurable to function as one of the following:

- a general purpose I/O
- an analog input to the comparator
- In-Circuit Serial Programming™ clock

FIGURE 4-2: BLOCK DIAGRAM OF RA1



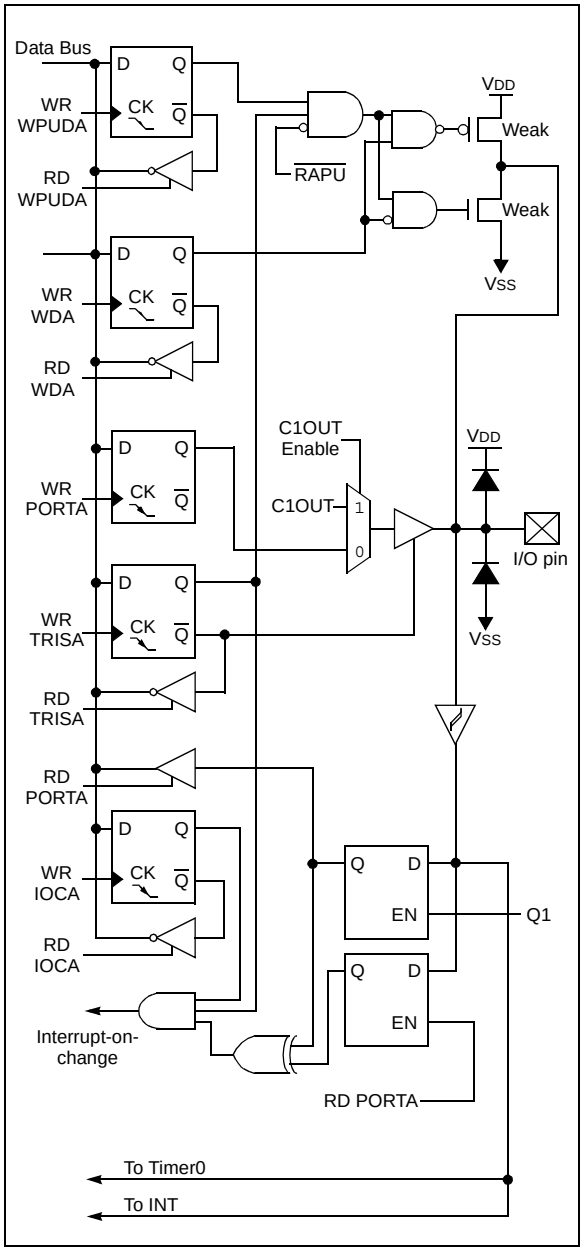
Note 1: Comparator mode determines Analog Input mode.

4.2.4.3 RA2/T0CKI/INT/C1OUT

Figure 4-3 shows the diagram for this pin. The RA2 pin is configurable to function as one of the following:

- a general purpose I/O
- the clock input for Timer0
- an external edge-triggered interrupt
- a digital output from the comparator

FIGURE 4-3: BLOCK DIAGRAM OF RA2



6.2.1 INTERNAL CLOCK SOURCE

When the internal clock source is selected the TMR1H:TMR1L register pair will increment on multiples of TCY as determined by the Timer1 prescaler.

6.2.2 EXTERNAL CLOCK SOURCE

When the external clock source is selected, the Timer1 module may work as a timer or a counter.

When counting, Timer1 is incremented on the rising edge of the external clock input T1CKI. In addition, the Counter mode clock can be synchronized to the microcontroller system clock or run asynchronously.

In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge after one or more of the following conditions:

- Timer1 is enabled after POR or BOR Reset
- A write to TMR1H or TMR1L
- T1CKI is high when Timer1 is disabled and when Timer1 is reenabled T1CKI is low. See Figure 6-2.

6.3 Timer1 Prescaler

Timer1 has four prescaler options allowing 1, 2, 4 or 8 divisions of the clock input. The T1CKPS bits of the T1CON register control the prescale counter. The prescale counter is not directly readable or writable; however, the prescaler counter is cleared upon a write to TMR1H or TMR1L.

6.4 Timer1 Oscillator

A low-power 32.768 kHz crystal oscillator is built-in between pins OSC1 (input) and OSC2 (amplifier output). The oscillator is enabled by setting the T1OSCEN control bit of the T1CON register. The oscillator will continue to run during Sleep.

The Timer1 oscillator is shared with the system LP oscillator. Thus, Timer1 can use this mode only when the primary system clock is derived from the internal oscillator or when in LP oscillator mode. The user must provide a software time delay to ensure proper oscillator start-up.

TRISA5 and TRISA4 bits are set when the Timer1 oscillator is enabled. RA5 and RA4 bits read as '0' and TRISA5 and TRISA4 bits read as '1'.

Note:	The oscillator requires a start-up and stabilization time before use. Thus, T1OSCEN should be set and a suitable delay observed prior to enabling Timer1.

6.5 Timer1 Operation in Asynchronous Counter Mode

If control bit $\overline{\text{T1SYNC}}$ of the T1CON register is set, the external clock input is not synchronized. The timer continues to increment asynchronous to the internal phase clocks. The timer will continue to run during Sleep and can generate an interrupt on overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (see **Section 6.5.1 "Reading and Writing Timer1 in Asynchronous Counter Mode"**).

Note:	When switching from synchronous to asynchronous operation, it is possible to skip an increment. When switching from asynchronous to synchronous operation, it is possible to produce a single spurious increment.

6.5.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L while the timer is running from an external asynchronous clock will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the TMR1H:TTMR1L register pair.

6.6 Timer1 Gate

Timer1 gate source is software configurable to be the $\overline{\text{T1G}}$ pin or the output of Comparator 2. This allows the device to directly time external events using $\overline{\text{T1G}}$ or analog events using Comparator 2. See the CMCON1 register (Register 7-3) for selecting the Timer1 gate source. This feature can simplify the software for a Delta-Sigma A/D converter and many other applications. For more information on Delta-Sigma A/D converters, see the Microchip web site (www.microchip.com).

Note:	TMR1GE bit of the T1CON register must be set to use either $\overline{\text{T1G}}$ or C2OUT as the Timer1 gate source. See Register 7-3 for more information on selecting the Timer1 gate source.

Timer1 gate can be inverted using the T1GINV bit of the T1CON register, whether it originates from the $\overline{\text{T1G}}$ pin or Comparator 2 output. This configures Timer1 to measure either the active-high or active-low time between events.

FIGURE 7-8: COMPARATOR INTERRUPT TIMING W/O CMCON0 READ

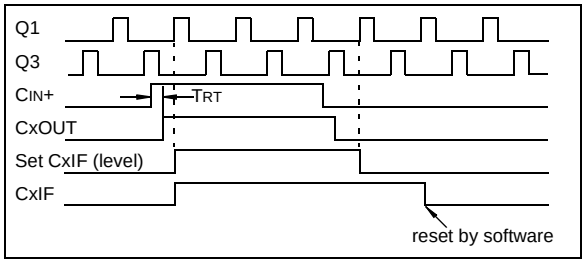
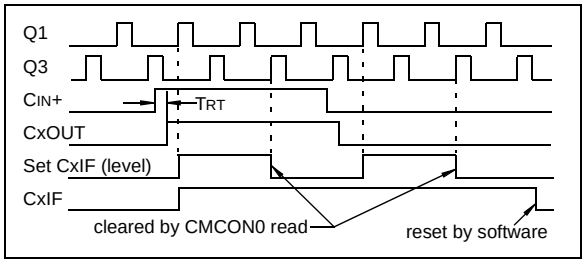


FIGURE 7-9: COMPARATOR INTERRUPT TIMING WITH CMCON0 READ



Note 1: If a change in the CMCON0 register (CxOUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CxIF of the PIR1 register interrupt flag may not get set.

2: When either comparator is first enabled, bias circuitry in the Comparator module may cause an invalid output from the comparator until the bias circuitry is stable. Allow about 1 µs for bias settling then clear the mismatch condition and interrupt flags before enabling comparator interrupts.

7.11 Comparator Voltage Reference

The Comparator Voltage Reference module provides an internally generated voltage reference for the comparators. The following features are available:

- Independent from Comparator operation
- Two 16-level voltage ranges
- Output clamped to VSS
- Ratiometric with VDD
- Fixed Voltage Reference

The VRCON register (Register 7-5) controls the Voltage Reference module shown in Figure 7-10.

7.11.1 INDEPENDENT OPERATION

The comparator voltage reference is independent of the comparator configuration. Setting the VREN bit of the VRCON register will enable the voltage reference.

7.11.2 OUTPUT VOLTAGE SELECTION

The CVREF voltage reference has 2 ranges with 16 voltage levels in each range. Range selection is controlled by the VRR bit of the VRCON register. The 16 levels are set with the VR<3:0> bits of the VRCON register.

The CVREF output voltage is determined by the following equations:

EQUATION 7-1: CVREF OUTPUT VOLTAGE (INTERNAL CVREF)

$$VRR = 1 \text{ (low range):}$$
$$CVREF = (VR<3:0>/24) \times VDD$$
$$VRR = 0 \text{ (high range):}$$
$$CVREF = (VDD/4) + (VR<3:0> \times VDD/32)$$

EQUATION 7-2: CVREF OUTPUT VOLTAGE (EXTERNAL CVREF)

$$VRR = 1 \text{ (low range):}$$
$$CVREF = (VR<3:0>/24) \times VLADDER$$
$$VRR = 0 \text{ (high range):}$$
$$CVREF = (VLADDER/4) + (VR<3:0> \times VLADDER/32)$$
$$VLADDER = VDD \text{ or } ([VREF+] - [VREF-]) \text{ or } VREF+$$

The full range of VSS to VDD cannot be realized due to the construction of the module. See Figure 7-10.

7.11.3 OUTPUT CLAMPED TO VSS

The CVREF output voltage can be set to Vss with no power consumption by configuring VRCON as follows:

- VREN = 0
- VRR = 1
- VR<3:0> = 0000

This allows the comparator to detect a zero-crossing while not consuming additional CVREF module current.

7.11.4 OUTPUT RATIOMETRIC TO VDD

The comparator voltage reference is VDD derived and therefore, the CVREF output changes with fluctuations in VDD. The tested absolute accuracy of the Comparator Voltage Reference can be found in **Section 15.0 "Electrical Specifications"**.

9.1 EECON1 AND EECON2 Registers

EECON1 is the control register with four low-order bits physically implemented. The upper four bits are non-implemented and read as '0's.

Control bits RD and WR initiate read and write, respectively. These bits cannot be cleared, only set in software. They are cleared in hardware at completion of the read or write operation. The inability to clear the WR bit in software prevents the accidental, premature termination of a write operation.

The WREN bit, when set, will allow a write operation. On power-up, the WREN bit is clear. The WRERR bit is set when a write operation is interrupted by a $\overline{\text{MCLR}}$ Reset, or a WDT Time-out Reset during normal operation. In these situations, following Reset, the user can check the WRERR bit, clear it and rewrite the location. The data and address will be cleared. Therefore, the EEDAT and EEADR registers will need to be re-initialized.

Interrupt flag, EEIF bit of the PIR1 register, is set when write is complete. This bit must be cleared in software.

EECON2 is not a physical register. Reading EECON2 will read all '0's. The EECON2 register is used exclusively in the data EEPROM write sequence.

Note:	The EECON1, EEDAT and EEADR registers should not be modified during a data EEPROM write (WR bit = 1).

REGISTER 9-3: EECON1: EEPROM CONTROL REGISTER

U-0	U-0	U-0	U-0	R/W-x	R/W-0	R/S-0	R/S-0
—	—	—	—	WRERR	WREN	WR	RD
bit 7							bit 0

Legend:			
S = Bit can only be set			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-4 **Unimplemented:** Read as '0'

bit 3 **WRERR:** EEPROM Error Flag bit
- 1 = A write operation is prematurely terminated (any $\overline{\text{MCLR}}$ Reset, any WDT Reset during normal operation or BOR Reset)
- 0 = The write operation completed

bit 2 **WREN:** EEPROM Write Enable bit
- 1 = Allows write cycles
- 0 = Inhibits write to the data EEPROM

bit 1 **WR:** Write Control bit
- 1 = Initiates a write cycle (The bit is cleared by hardware once write is complete. The WR bit can only be set, not cleared, in software.)
- 0 = Write cycle to the data EEPROM is complete

bit 0 **RD:** Read Control bit
- 1 = Initiates an EEPROM read (Read takes one cycle. RD is cleared in hardware. The RD bit can only be set, not cleared, in software.)
- 0 = Does not initiate an EEPROM read

9.2 Reading the EEPROM Data Memory

To read a data memory location, the user must write the address to the EEADR register and then set control bit RD of the EECON1 register, as shown in Example 9-1. The data is available, in the very next cycle, in the EEDAT register. Therefore, it can be read in the next instruction. EEDAT holds this value until another read, or until it is written to by the user (during a write operation).

EXAMPLE 9-1: DATA EEPROM READ

```
BANKSEL  EEADR          ;
MOVLW    CONFIG_ADDR    ;
MOVWF    EEADR          ;Address to read
BSF      EECON1,RD      ;EE Read
MOVF     EEDAT,W        ;Move data to W
```

9.3 Writing to the EEPROM Data Memory

To write an EEPROM data location, the user must first write the address to the EEADR register and the data to the EEDAT register. Then the user must follow a specific sequence to initiate the write for each byte, as shown in Example 9-2.

The write will not initiate if the above sequence is not exactly followed (write 55h to EECON2, write AAh to EECON2, then set WR bit) for each byte. We strongly recommend that interrupts be disabled during this code segment. A cycle count is executed during the required sequence. Any number that is not equal to the required cycles to execute the required sequence will prevent the data from being written into the EEPROM.

Additionally, the WREN bit in EECON1 must be set to enable write. This mechanism prevents accidental writes to data EEPROM due to errant (unexpected) code execution (i.e., lost programs). The user should keep the WREN bit clear at all times, except when updating EEPROM. The WREN bit is not cleared by hardware.

After a write sequence has been initiated, clearing the WREN bit will not affect this write cycle. The WR bit will be inhibited from being set unless the WREN bit is set.

At the completion of the write cycle, the WR bit is cleared in hardware and the EE Write Complete Interrupt Flag bit (EEIF) is set. The user can either enable this interrupt or poll this bit. The EEIF bit of the PIR1 register must be cleared by software.

EXAMPLE 9-2: DATA EEPROM WRITE

```
          BANKSEL EEADR          ;
          BSF     EECON1,WREN    ;Enable write
          BCF     INTCON,GIE     ;Disable INTs
Required  MOVLW   55h            ;Unlock write
Sequence  MOVWF   EECON2         ;
          MOVLW   AAh            ;
          MOVWF   EECON2         ;
          BSF     EECON1,WR      ;Start the write
          BSF     INTCON,GIE     ;Enable INTS
```

9.4 Write Verify

Depending on the application, good programming practice may dictate that the value written to the data EEPROM should be verified (see Example 9-3) to the desired value to be written.

EXAMPLE 9-3: WRITE VERIFY

```
BANKSEL  EEDAT      ;
MOVF     EEDAT,W    ;EEDAT not changed
                    ;from previous write
BSF      EECON1,RD  ;YES, Read the
                    ;value written
XORWF    EEDAT,W    ;
BTFSS    STATUS,Z   ;Is data the same
GOTO     WRITE_ERR  ;No, handle error
:                   ;Yes, continue
```

9.4.1 USING THE DATA EEPROM

The data EEPROM is a high-endurance, byte addressable array that has been optimized for the storage of frequently changing information (e.g., program variables or other data that are updated often). When variables in one section change frequently, while variables in another section do not change, it is possible to exceed the total number of write cycles to the EEPROM (specification D124) without exceeding the total number of write cycles to a single byte (specifications D120 and D120A). If this is the case, then a refresh of the array must be performed. For this reason, variables that change infrequently (such as constants, IDs, calibration, etc.) should be stored in Flash program memory.

11.6 AGC Control

The AGC controls the variable attenuator to limit the internal signal voltage to avoid saturation of internal amplifiers and demodulators (Refer to **Section 11.4 "Variable Attenuator"**).

The signal levels from all 3 channels are combined such that AGC attenuates all 3 channels uniformly in respect to the channel with the strongest signal.

Note:	The AGC control function is accomplished by the device itself. The user cannot control its function.

11.7 Fixed Gain Amplifiers 1 and 2

FGA1 and FGA2 provides a maximum two-stage gain of 40 dB.

Note:	The user cannot control the gain of these two amplifiers.

11.8 Auto Channel Selection

The Auto Channel Selection feature is enabled if the Auto Channel Select bit AUTOCHSEL<8> in Configuration Register 5 (Register 11-6) is set, and disabled if the bit is cleared. When this feature is active (i.e., AUTOCHSE <8> = 1), the control circuit checks the demodulator output of each input channel immediately after the AGC settling time (T_{STAB}). If the output is high, it allows this channel to pass data, otherwise it is blocked.

The status of this operation is monitored by AFE Status Register 7 bits <8:6> (Register 11-8). These bits indicate the current status of the channel selection activity, and automatically updates for every Soft Reset period. The auto channel selection function resets after each Soft Reset (or after Inactivity timer time-out). Therefore, the blocked channels are reenabled after Soft Reset.

This feature can make the output signal cleaner by blocking any channel that was not high at the end of T_{AGC}. This function works only for demodulated data output, and is not applied for carrier clock or RSSI output.

11.9 Carrier Clock Detector

The Detector senses the input carrier cycles. The output of the Detector switches digitally at the signal carrier frequency. Carrier clock output is available when the output is selected by the DATOUT bit in the AFE Configuration Register 1 (Register 11-2).

11.10 Demodulator

The Demodulator consists of a full-wave rectifier, low pass filter, peak detector and Data Slicer that detects the envelope of the input signal.

11.11 Data Slicer

The Data Slicer consists of a reference generator and comparator. The Data Slicer compares the input with the reference voltage. The reference voltage comes from the minimum modulation depth requirement setting and input peak voltage. The data from all 3 channels are OR'd together and sent to the output enable filter.

11.12 Output Enable Filter

The Output Enable Filter enables the LFDATA output once the incoming signal meets the wake-up sequence requirements (see **Section 11.15 "Configurable Output Enable Filter"**).

11.13 RSSI (Received Signal Strength Indicator)

The RSSI provides a current which is proportional to the input signal amplitude (see **Section 11.31.3 "Received Signal Strength Indicator (RSSI) Output"**).

11.14 Analog Front-End Timers

The AFE has an internal 32 kHz RC oscillator. The oscillator is used in several timers:

- Inactivity timer
- Alarm timer
- Pulse Width timer
- Period timer
- AGC settling timer

11.14.1 RC OSCILLATOR

The RC oscillator is low power, 32 kHz ± 10% over temperature and voltage variations.

FIGURE 11-3: BIDIRECTIONAL PASSIVE KEYLESS ENTRY (PKE) SYSTEM APPLICATION EXAMPLE

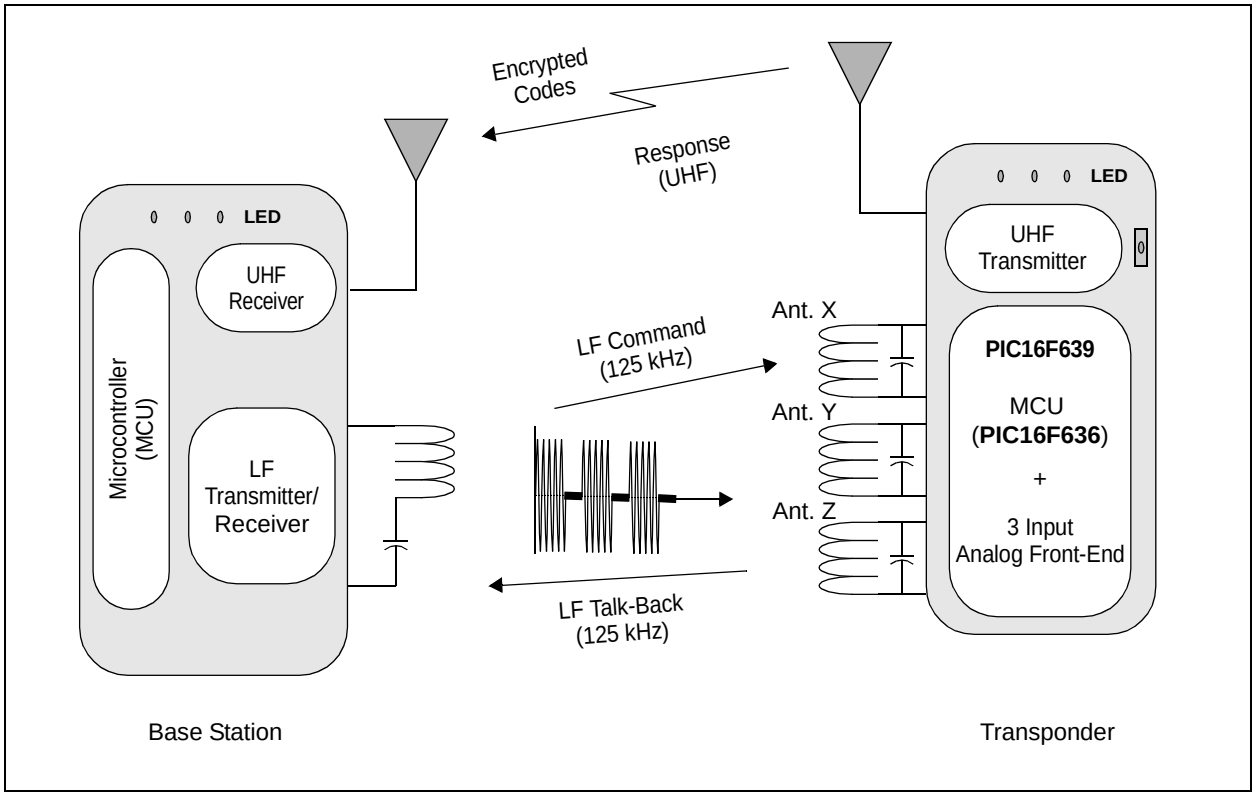
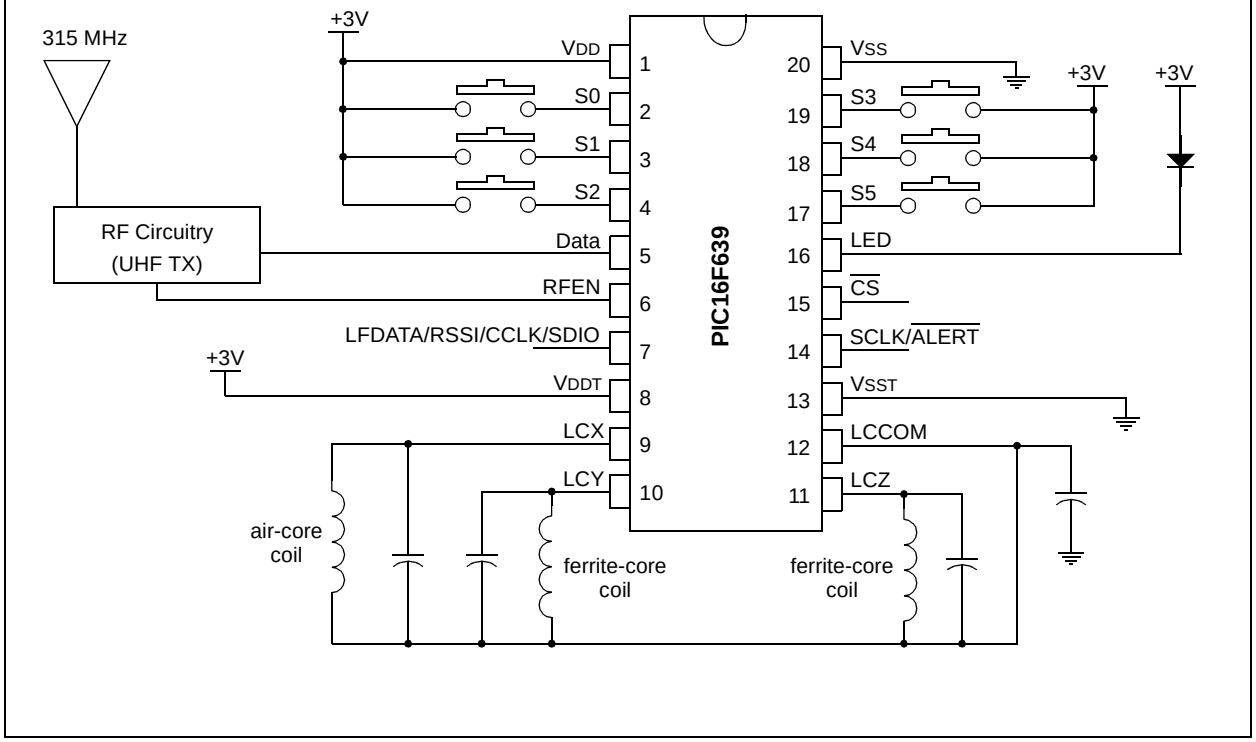
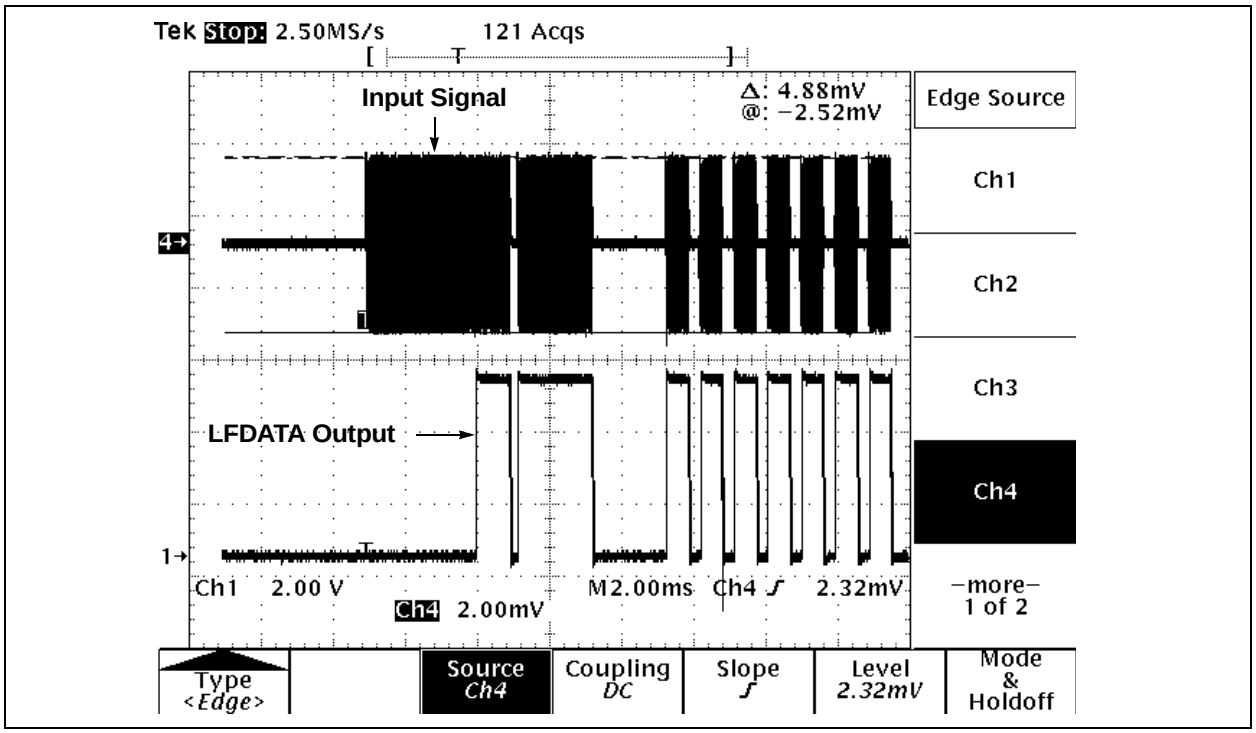


FIGURE 11-4: PASSIVE KEYLESS ENTRY (PKE) TRANSPONDER CONFIGURATION EXAMPLE



Case I. When Output Enable Filter is disabled: Demodulated output is available immediately after the AGC stabilization time (TAGC). Figure 11-10 shows an example of demodulated output when the Output Enable Filter is disabled.

FIGURE 11-10: INPUT SIGNAL AND DEMODULATOR OUTPUT WHEN THE OUTPUT ENABLE FILTER IS DISABLED



Case II. When Output Enable Filter is enabled: Demodulated output is available only if the incoming signal meets the enable filter timing criteria that is defined in the Configuration Register 0 (Register 11-1). If the criteria is met, the output is available after the low timing (TOEL) of the Enable Filter. Figure 11-11 and Figure 11-12 shows examples of demodulated output when the Output Enable Filter is enabled.

11.31.3.1 ANALOG-TO-DIGITAL DATA CONVERSION OF RSSI SIGNAL

The AFE's RSSI output is an analog current. It needs an external Analog-to-Digital (ADC) data conversion device for digitized output. The ADC data conversion can be accomplished by using a stand-alone external ADC device or by firmware utilizing MCU's internal comparator along with a few external resistors and a capacitor. For slope ADC implementations, the external capacitor at the LFDATA pad needs to be discharged before data sampling. For this purpose, the internal pull-down MOSFET on the LFDATA pad can be utilized. The MOSFET can be turned on or off with bit RSSIFET<8> of the Configuration Register 2 (Register 11-3). When it is turned on, the internal MOSFET provides a discharge path for the external capacitor. This MOSFET option is valid only if RSSI output is selected and not controllable by users for demodulated or carrier clock output options.

See separate application notes for various external ADC implementation methods for this device.

11.32 AFE Configuration

11.32.1 SPI COMMUNICATION

The AFE SPI interface communication is used to read or write the AFE's Configuration registers and to send command only messages. For the SPI interface, the device has three pads; $\overline{CS}$, SCLK/$\overline{ALERT}$, and LFDATA/RSSI/CCLK/SDIO. Figure 11-15, Figure 11-14, Figure 11-16 and Figure 11-17 shows examples of the SPI communication sequences.

When the device powers up, these pins will be high-impedance inputs until firmware modifies them appropriately. The AFE pins connected to the MCU pins will be as follows.

$\overline{CS}$

- Pin is permanently an input with an internal pull-up.

SCLK/$\overline{ALERT}$

- Pin is an open collector output when $\overline{CS}$ is high. An internal pull-up resistor exists internal to the AFE to ensure no spurious SPI communication between powering and the MCU configuring its pins. This pin becomes the SPI clock input when $\overline{CS}$ is low.

LFDATA/RSSI/CCLK/SDIO

- Pin is a digital output (LFDATA) so long as $\overline{CS}$ is high. During SPI communication, the pin is the SPI data input (SDI) unless performing a register Read, where it will be the SPI data output (SDO).

FIGURE 11-16: POWER-UP SEQUENCE

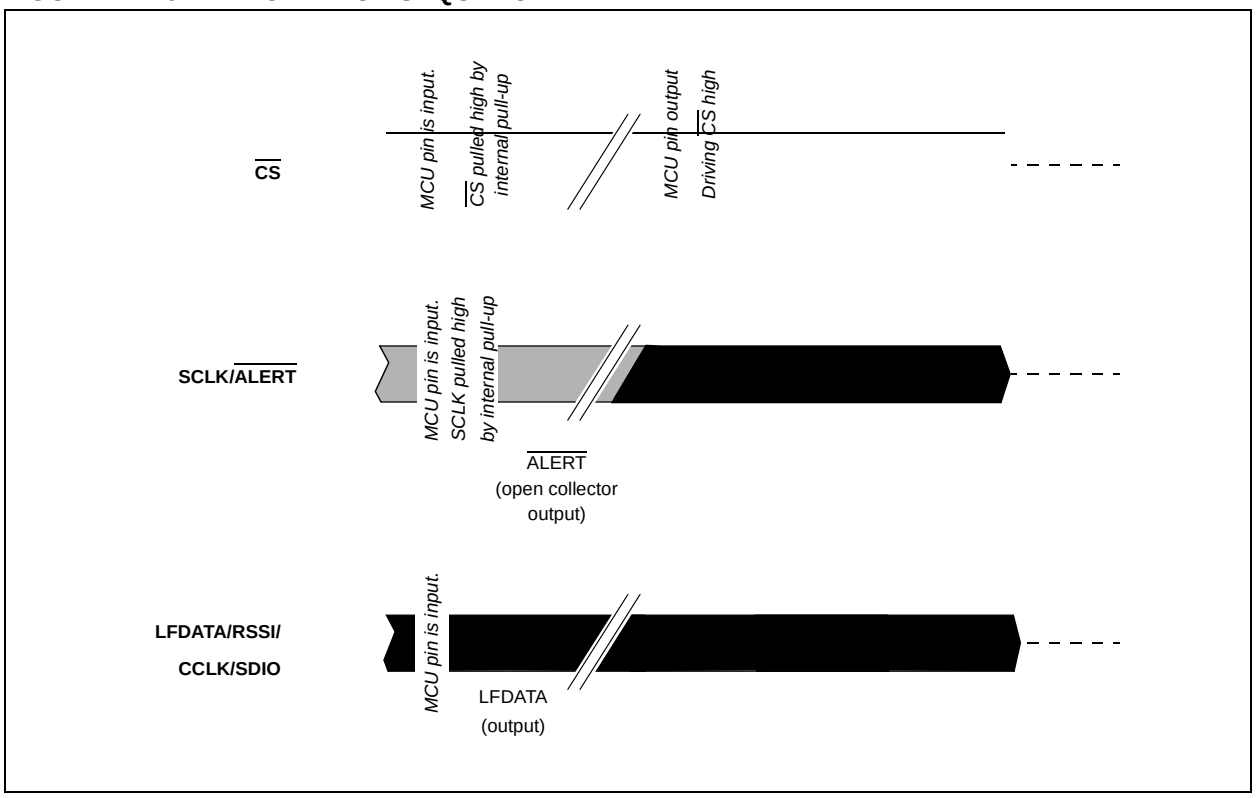
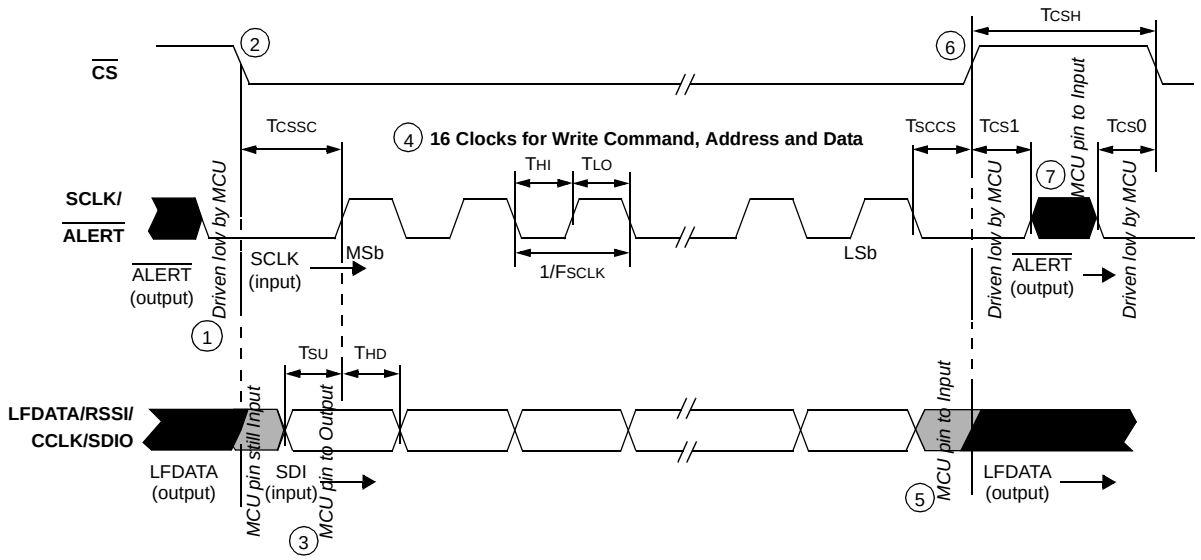


FIGURE 11-17: SPI WRITE SEQUENCE



MCU SPI Write Details:

1. Drive the AFE's open collector $\overline{\text{ALERT}}$ output low.
   - To ensure no false clocks occur when $\overline{\text{CS}}$ drops.
2. Drop $\overline{\text{CS}}$.
   - AFE SCLK/$\overline{\text{ALERT}}$ becomes SCLK input.
   - LFDATA/RSSI/CCLK/SDIO becomes SDI input.
3. Change LFDATA/RSSI/CCLK/SDIO connected pin to output.
   - Driving SPI data.
4. Clock in 16-bit SPI Write sequence - command, address, data and parity bit.
   - Command, address, data and parity bit.
5. Change LFDATA/RSSI/CCLK/SDIO connected pin to input.
6. Raise $\overline{\text{CS}}$ to complete the SPI Write.
7. Change SCLK/$\overline{\text{ALERT}}$ back to input.

12.3 Power-on Reset

The on-chip POR circuit holds the chip in Reset until V_{DD} has reached a high enough level for proper operation. To take advantage of the POR, simply connect the $\overline{MCLR}$ pin through a resistor to V_{DD}. This will eliminate external RC components usually needed to create Power-on Reset. A maximum rise time for V_{DD} is required. See **Section 15.0 "Electrical Specifications"** for details. If the BOR is enabled, the maximum rise time specification does not apply. The BOR circuitry will keep the device in Reset until V_{DD} reaches V_{BOD} (see **Section 12.6 "Brown-out Reset (BOR)"**).

Note:	The POR circuit does not produce an internal Reset when V_{DD} declines. To re-enable the POR, V_{DD} must reach V_{SS} for a minimum of 100 µs.

When the device starts normal operation (exits the Reset condition), device operating parameters (i.e., voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

For additional information, refer to the Application Note *AN607, "Power-up Trouble Shooting"* (DS00607).

12.4 Wake-up Reset (WUR)

The PIC12F635/PIC16F636/639 has a modified wake-up from Sleep mechanism. When waking from Sleep, the WUR function resets the device and releases Reset when V_{DD} reaches an acceptable level.

If the $\overline{WURE}$ bit is enabled ('0') in the Configuration Word register, the device will Wake-up Reset from Sleep through one of the following events:

1. On any event that causes a wake-up event. The peripheral must be enabled to generate an interrupt or wake-up, GIE state is ignored.
2. When WURE is enabled, RA3 will always generate an interrupt-on-change signal during Sleep.

The $\overline{WUR}$, $\overline{POR}$ and $\overline{BOR}$ bits in the PCON register and the $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device Reset.

To allow WUR upon RA3 change:

1. Enable the WUR function, $\overline{WURE}$ Configuration Bit = 0.
2. Enable RA3 as an input, MCLRE Configuration Bit = 0.
3. Read PORTA to establish the current state of RA3.
4. Execute SLEEP instruction.
5. When RA3 changes state, the device will wake-up and then reset. The $\overline{WUR}$ bit in PCON will be cleared to '0'.

12.4.1 POWER-UP TIMER (PWRT)

The Power-up Timer provides a fixed 64 ms (nominal) time-out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates from the 31 kHz LFINTOSC oscillator. For more information, see **Section 3.5 "Internal Clock Modes"**. The chip is kept in Reset as long as PWRT is active. The PWRT delay allows the V_{DD} to rise to an acceptable level. A Configuration bit, $\overline{PWRTE}$, can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should be enabled when Brown-out Reset is enabled, although it is not required.

The Power-up Timer delay will vary from chip-to-chip due to:

- V_{DD} variation
- Temperature variation
- Process variation

See DC parameters for details (**Section 15.0 "Electrical Specifications"**).

Note:	Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100 Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin, rather than pulling this pin directly to V_{SS}.

12.5 $\overline{MCLR}$

PIC12F635/PIC16F636/639 has a noise filter in the $\overline{MCLR}$ Reset path. The filter will ignore small pulses.

It should be noted that a WDT Reset does not drive $\overline{MCLR}$ pin low. See Figure 12-2 for the recommended $\overline{MCLR}$ circuit.

An internal $\overline{MCLR}$ option is enabled by clearing the MCLRE bit in the Configuration Word register. When cleared, $\overline{MCLR}$ is internally tied to V_{DD} and an internal weak pull-up is enabled for the $\overline{MCLR}$ pin. In-Circuit Serial Programming is not affected by selecting the internal $\overline{MCLR}$ option.

FIGURE 16-10: IDD vs. VDD OVER FOSC (LP MODE)

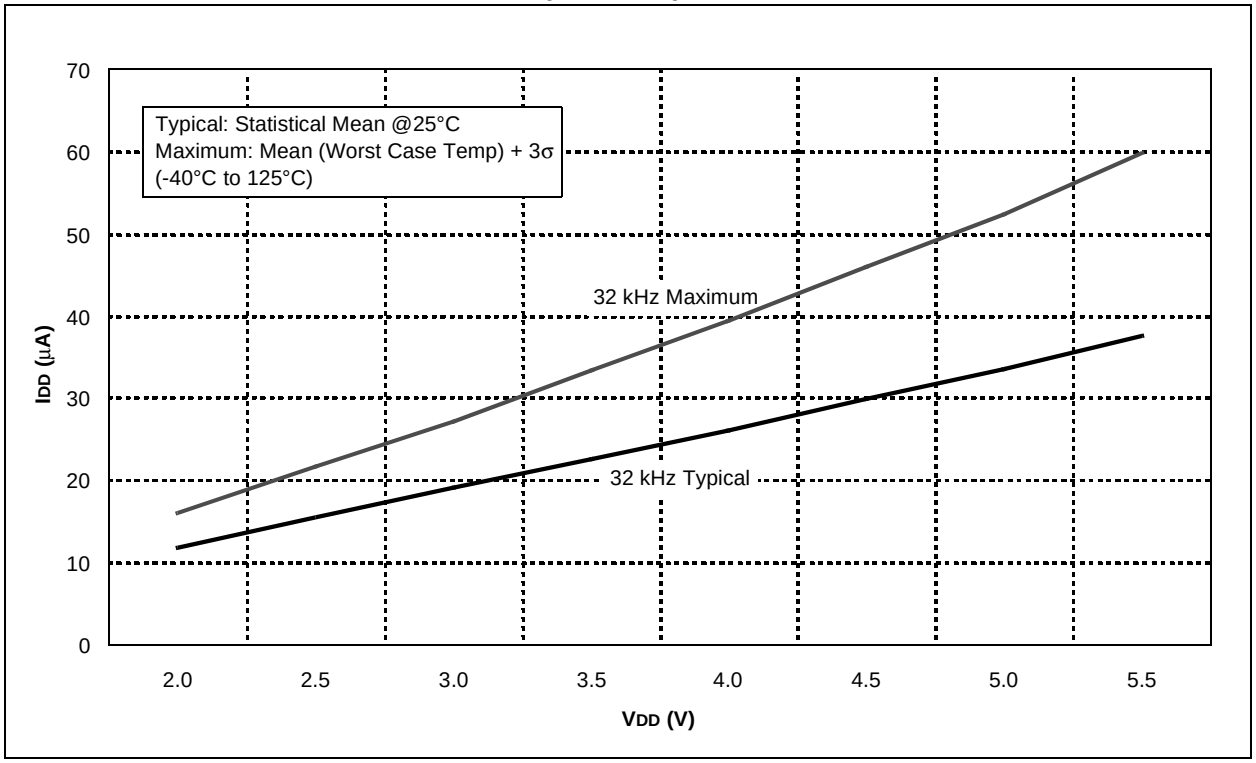


FIGURE 16-11: TYPICAL IDD vs. FOSC OVER VDD (HFINTOSC MODE)

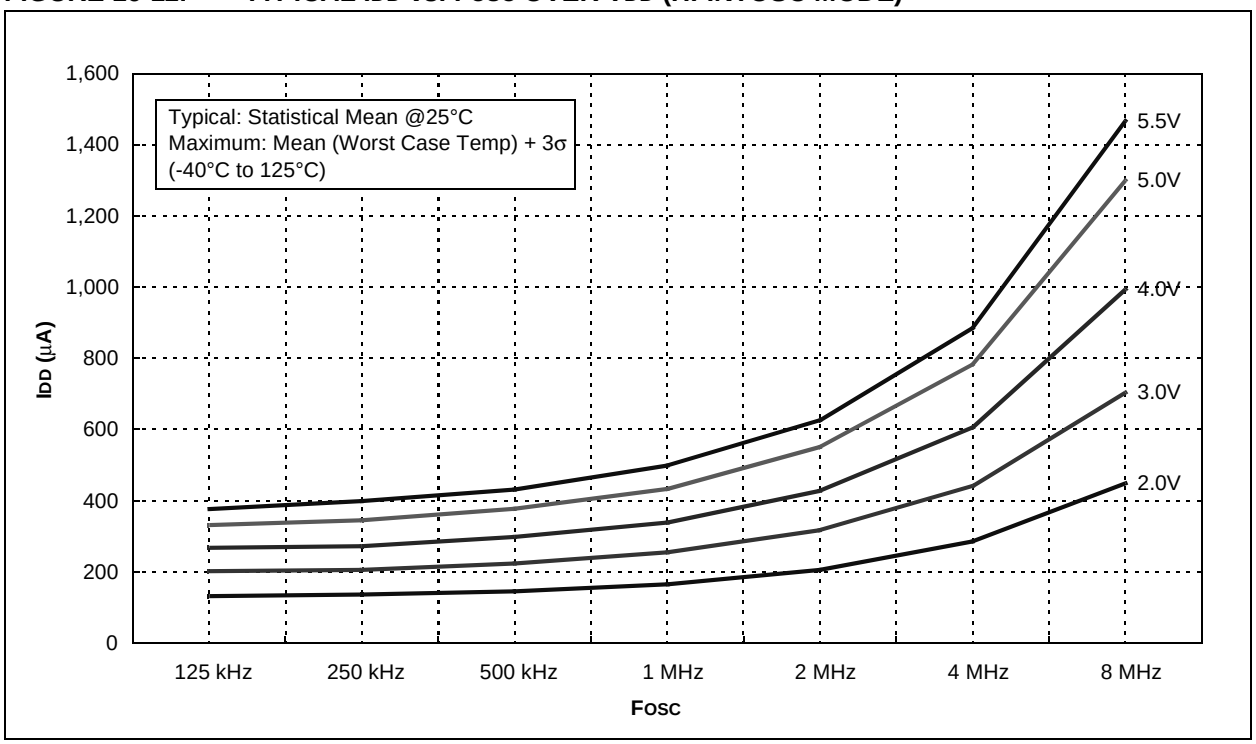


FIGURE 16-26: VOH vs. IOH OVER TEMPERATURE (VDD = 5.0V)

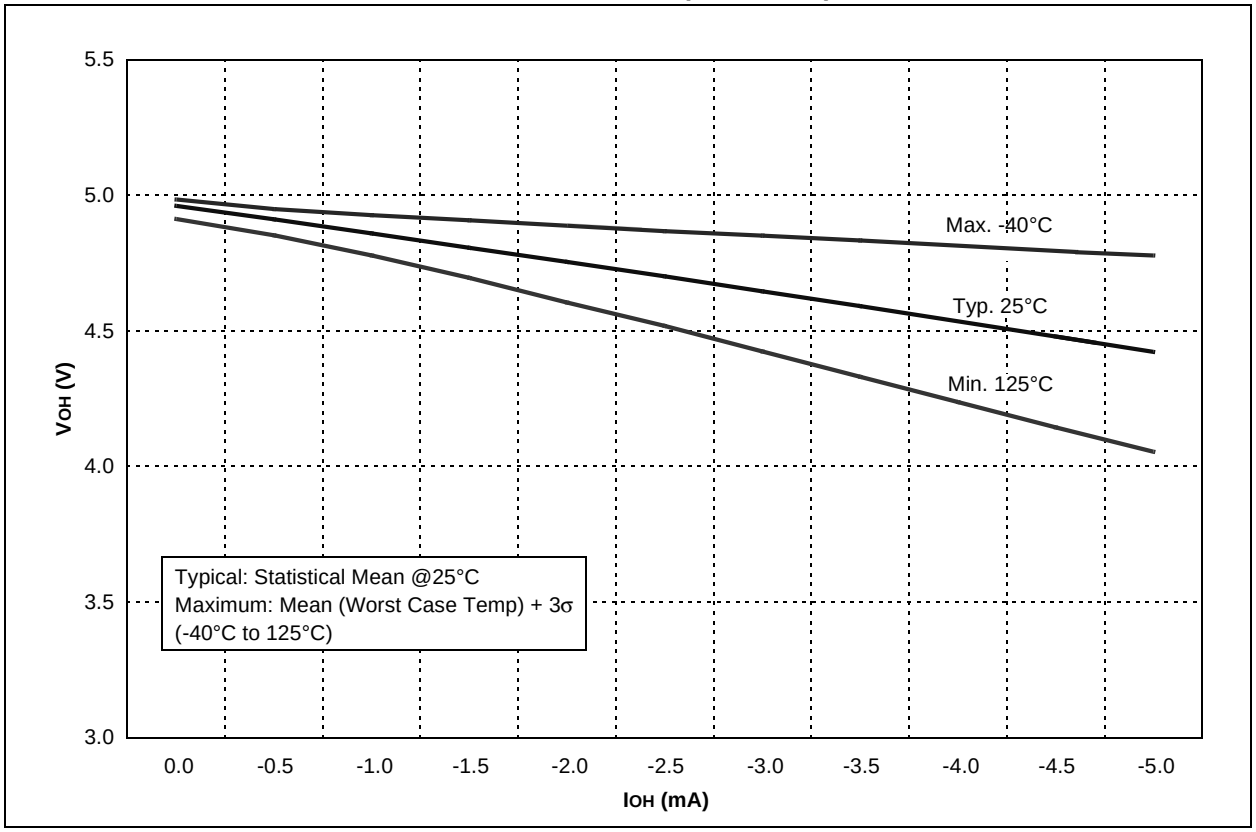
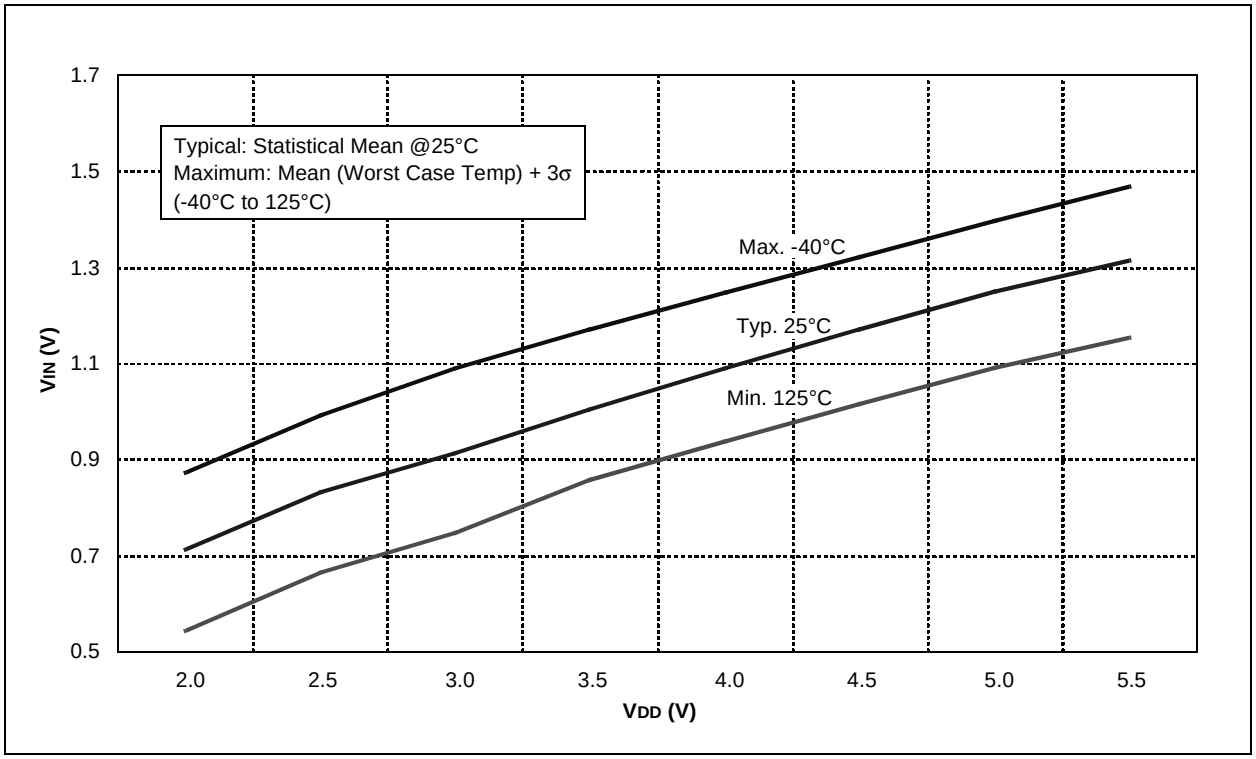
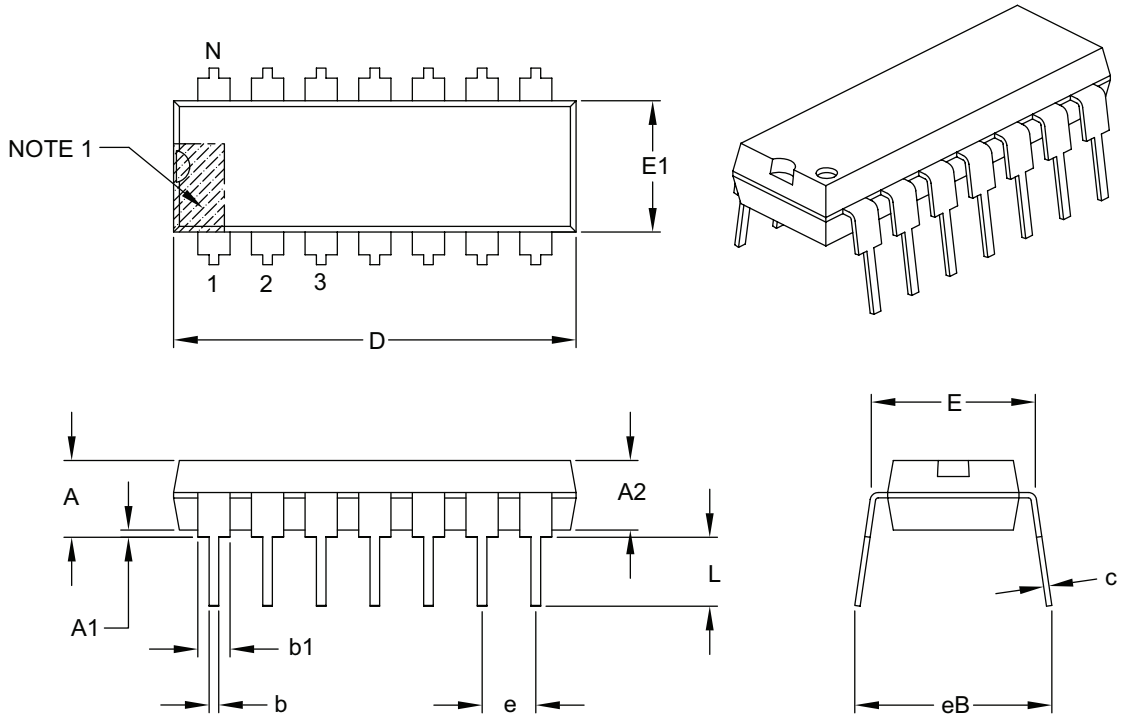


FIGURE 16-27: TTL INPUT THRESHOLD VIN vs. VDD OVER TEMPERATURE



14-Lead Plastic Dual In-Line (P or PD) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.735	.750	.775
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

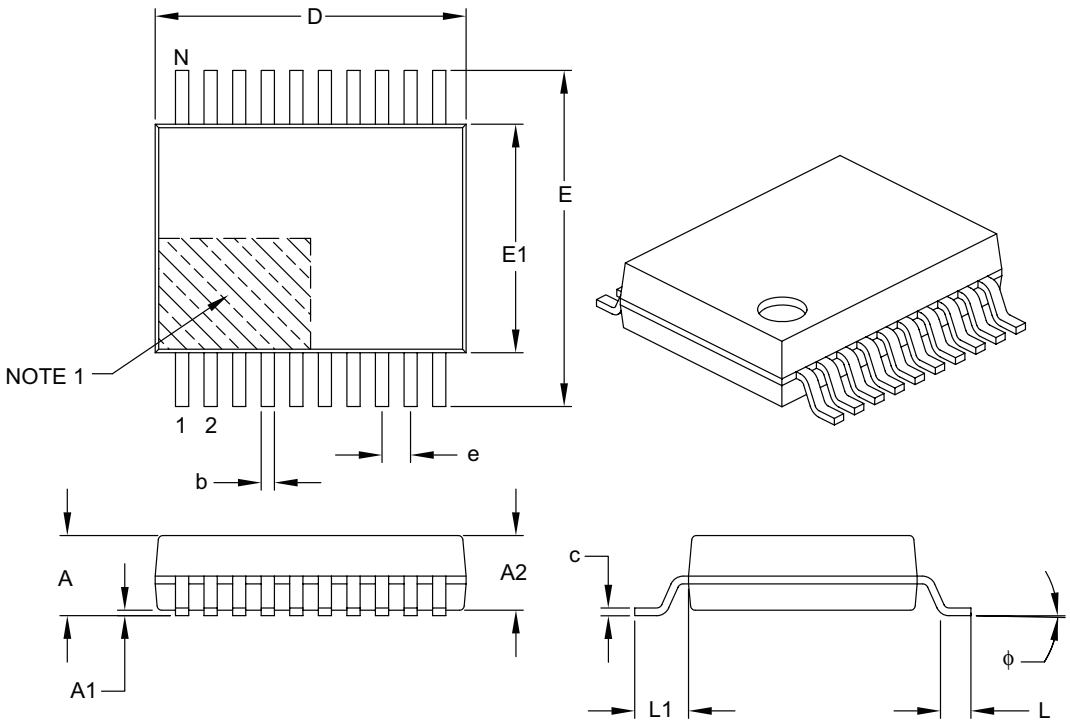
1. Pin 1 visual index feature may vary, but must be located with the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-005B

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B

READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this document.

To: Technical Publications Manager Total Pages Sent _____

RE: Reader Response

From: Name _____

Company _____

Address _____

City / State / ZIP / Country _____

Telephone: (_____) _____ - _____ FAX: (_____) _____ - _____

Application (optional):

Would you like a reply? ___Y ___N

Device: PIC12F635/PIC16F636/639 Literature Number: DS41232D

Questions:

1. What are the best features of this document?

2. How does this document meet your hardware and software development needs?

3. Do you find the organization of this document easy to follow? If not, why?

4. What additions to the document do you think would enhance the structure and subject?

5. What deletions from the document could be made without affecting the overall usefulness?

6. Is there any incorrect or misleading information (what and where)?

7. How would you improve this document?